

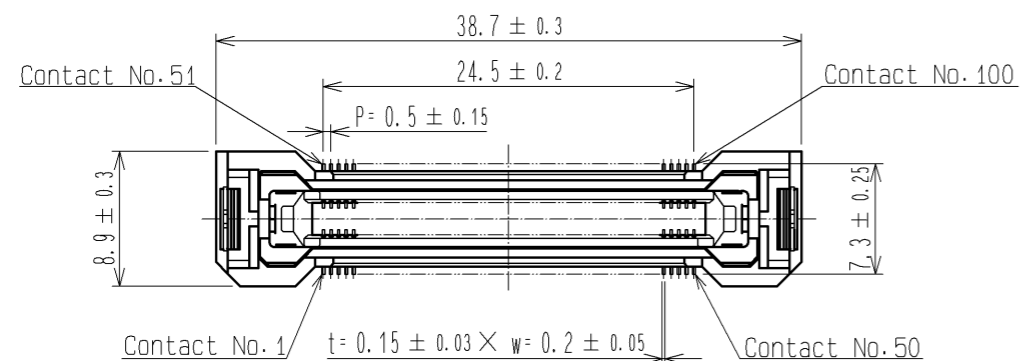
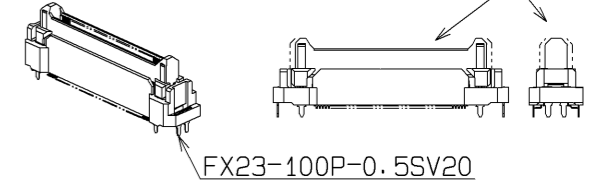
RECOMMENDED LAND PATTERN DIMENSION OF PCB

△ (PCB THICKNESS: t=1.6mm)

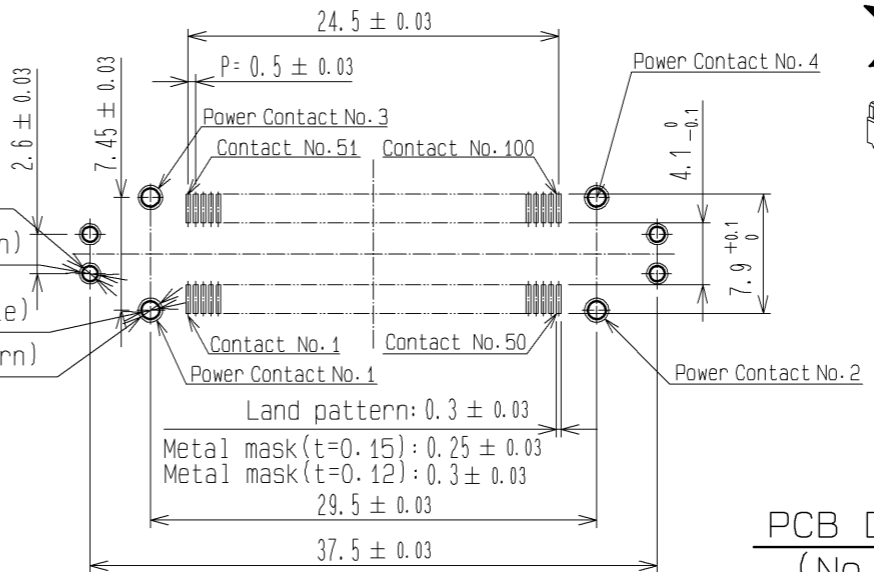
③ FLOATING RANGE

Y DIRECTION: ±0.6mm

X DIRECTION: ±0.6mm



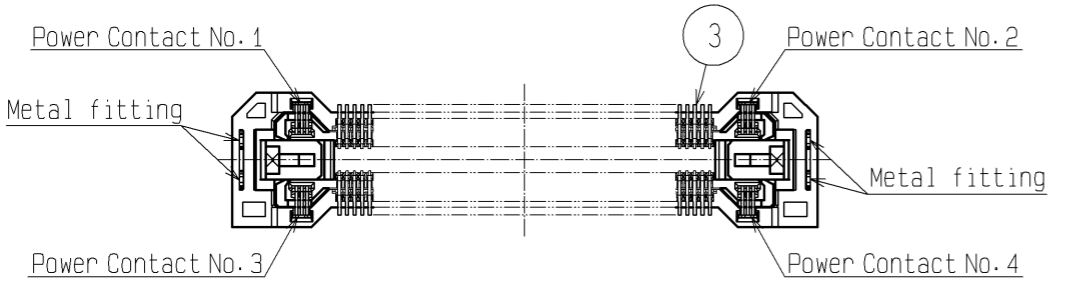
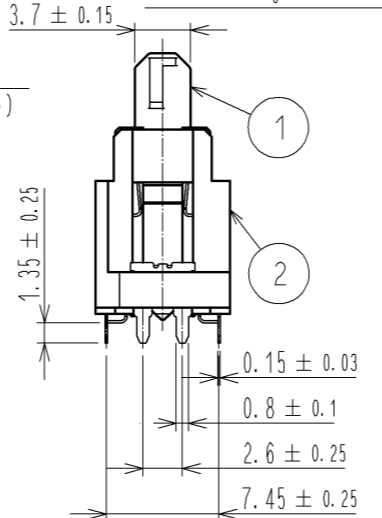
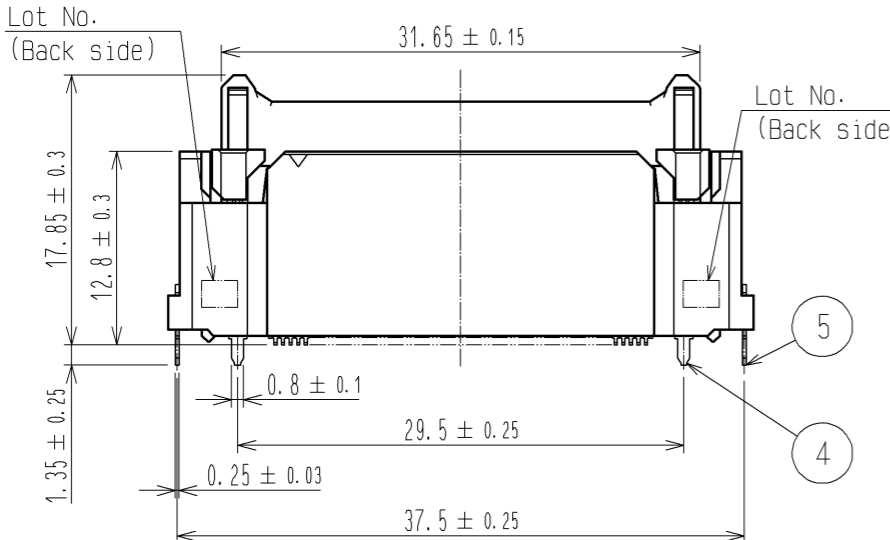
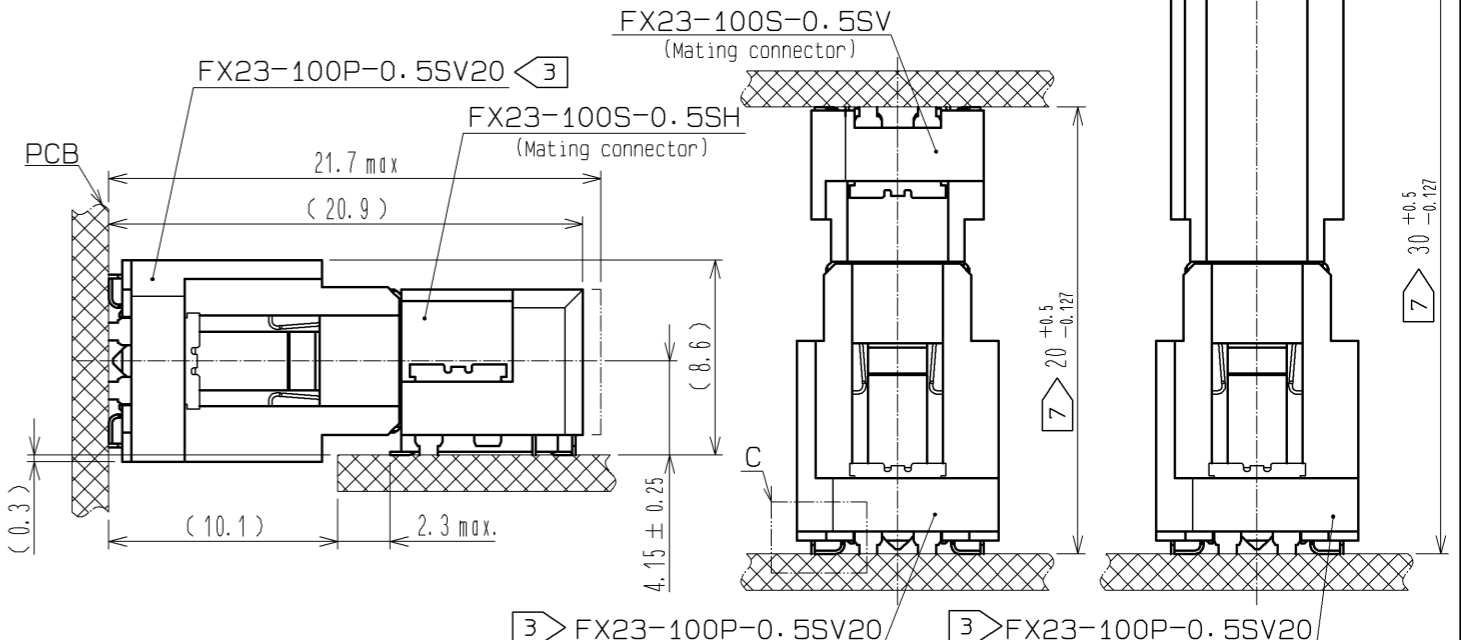
- 4X $\phi 1^{+0.1}_0$ (Through-hole)
- 4X $\phi 1.4^{+0.2}_0$ (Land pattern)
- 4X $\phi 1.2^{+0.1}_0$ (Through-hole)
- 4X $\phi 1.6^{+0.2}_0$ (Land pattern)



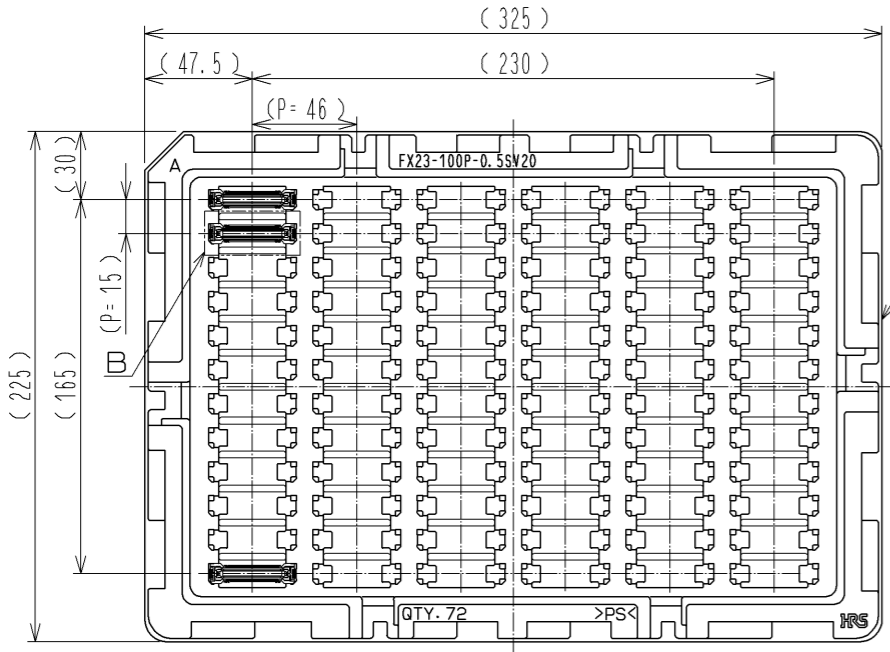
FX23-100P-0.5SV20

FX23-100S-0.5SV10 (Mating connector)

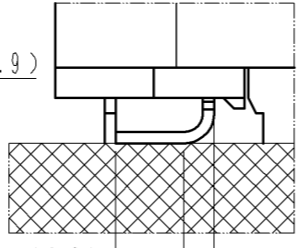
PCB DISTANCE (No scale)



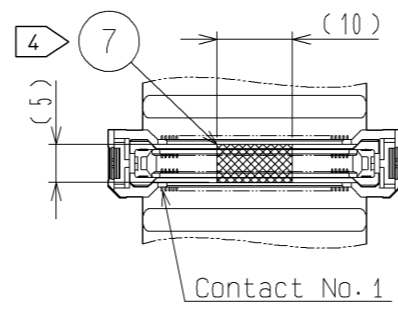
② DRAWING FOR PACKING (No scale)



C (10 : 1)



B (1 : 1)



- 1 Lead CO-Planarity is 0.1mm MAX.
- 2 This is packaged in tray. (72pcs/tray)
- 3 Floating range of this connector is ±0.6mm MAX.
- 4 It shows the vacuum pickup area. Remove the mylar tape before mating connectors.
- 5 Blemish and hit mark can be occurred through out the manufacturing process which doesn't affect quality level.
- 6 The dimensions in parentheses are for references.
- 7 Please use the connectors within the specified PCB distance.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: GOLD 0.03 μm UNDER PLATING: NICKEL 1.3 μm	5	BRASS		LEAD AREA: TIN-PLATING 3 μm UNDER PLATING: NICKEL 1 μm
2	POLYAMIDE		BLACK UL94V-0	4	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: TIN-PLATING 1 μm UNDER PLATING: NICKEL 1.3 μm
1	POLYAMIDE		BLACK UL94V-0				
7	POLYIMIDE		(TAPE FOR VACUUM PICKUP)				
6	POLYSTYRENE		(TRAY)				

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	1	DIS-F-007547	TS.00NO	HS.OKAWA	14.09.04
APPROVED : HS. OKAWA			14.07.25	DRAWING NO. EDC3-353548-00		
CHECKED : KN. SHIBUYA			14.07.25	PART NO. FX23-100P-0.5SV20		
DESIGNED : TS.00NO			14.07.25	CODE NO. CL573-3105-6-00		
DRAWN : TS.00NO			14.07.25			